

25. An integrated heat spreader, comprising:

*Sub B* a surface having a central area and a channel, the channel to be recessed relative to the central area, the surface to be thermally coupled to a heat sink by a thermal interface material layer.

26. An integrated heat spreader as recited in claim 25, wherein a portion of the thermal interface material layer is disposed within the channel.

*q* 27. An integrated heat spreader as recited in claim 25, wherein the thermal interface material layer comprises solder.

28. An integrated heat spreader as recited in claim 25, wherein the channel is plated with a wetting layer.

29. An integrated heat spreader as recited in claim 29, wherein the wetting layer comprises gold on electrolytic nickel.

30. An integrated heat spreader as recited in claim 25, wherein the channel has a width of between about 0.5 mils to about 5.0 mils and a depth of between about 0.5 mils to about 5.0 mils.